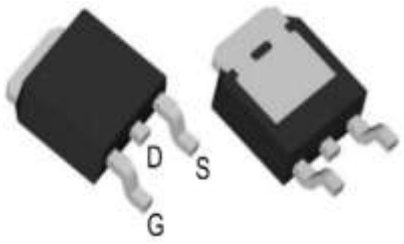
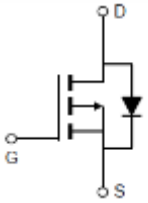
-100V_{DS}/±20V_{GS} P-Channel Enhancement Mode MOSFET

Features

- V_{DS}=-100V,I_D=-45A
- $R_{DS(ON)}$=52mΩ（TYP.）V_{GS}=-10V
- Reliable and Rugged
- Avalanche Rated
- Low On-Resistance
- High Current Capability

TO-252





Applications

- Load Switch
- Power management in portable/desktop PCs
- DC/DC conversion

Ordering Information

Device	package	Device Marking	Package Qty.
JMPL1025AK	TO-252	PL1025AK	2500/PCS

Absolute Maximum Ratings (T_C=25℃,unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V_{GS}=0V)	V_{DS}	-100	V
Gate-Source Voltage (V_{GS}=0V,static)	V_{GS}	±20	V
Continuous Drain Current (T_C=25℃)	I_D	-45	A
Continuous Drain Current (T_C=100℃)		-28	A
Pulesd Drain Current	I_{DM}	-140	A
Avalanche Energy, Single Pulsed	E_{AS}	87	mJ
Maximum Power Dissipation (T_C=25℃)	P_D	140	W
Operating,Storage Temperature Range	T_J,T_{STG}	-55~150	℃

Electrical Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V,I_D=-250μA	-100	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-30V, V_{GS}=0V	-	-	-1	μA
Gate -Source Leakage Current	I_{GSS}	V_{GS}=±20V, V_{DS}=0V	-	-	±10	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}= V_{GS},I_D=-250μA	-1	-1.6	-2.5	V
Drain-Source On-stage Resistance	$R_{DS(ON)}$	V_{GS}=-10V,I_D=-1A	-	-	50	mΩ
		V_{GS}=-4.5V,I_D=-1A	-	-	60	

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance,Junction-to-Case	$R_{\theta JC}$	-	1.25	-	℃/ W
Thermal Resistance,Junction-to-Ambient	$R_{\theta JA}$	-	50	-	℃/ W

Dynamic Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	V_{DS}=-15V	-	2120	-	pF
Output capacitance	C_{oss}	V_{GS}=0V	-	194	-	
Reverse transfer capacitance	C_{rss}	f=1MHz	-	13	-	
Gate Resistance	R_g	f=1MHz	-	6	-	Ω
Total Gate Charge	Q_g	V_{DS}=-15V	-	40	-	nC
Gate Source Charge	Q_{gs}	V_{GS}=-10V	-	7.8	-	
Gate Drain Charge	Q_{gd}	I_D=-15A	-	8.6	-	
Turn-on delay Time	$t_{d(on)}$	V_{GS}=-10V	-	13	-	ns
Rise time	t_r	V_{DS}=-15V	-	39	-	
Turn-off delay Time	$t_{d(off)}$	R_L=1Ω	-	100	-	
Fall time	t_f	R_G=3Ω	-	105	-	

Reverse Diode Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Body Diode Forward Voltage	V_{SD}	V_{GS}=0V,I_{SD}=-1A	-	-	-1.2	V
Reverse Recovery Time	t_{rr}	V_{GS}=0V,I_{SD}=-15A	-	90	-	ns
Reverse Recovery Charge	Q_{rr}	d_i/d_t=100A/μs	-	70	-	nC

Electrical Characteristics Diagrames

Figure 1. On-Regin Characteristics

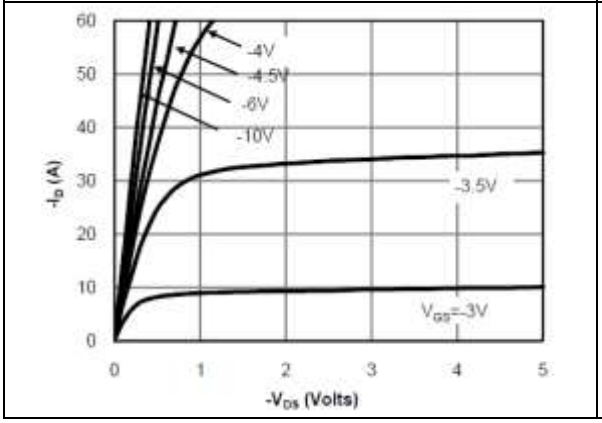


Figure 2. Transfer Characteristics

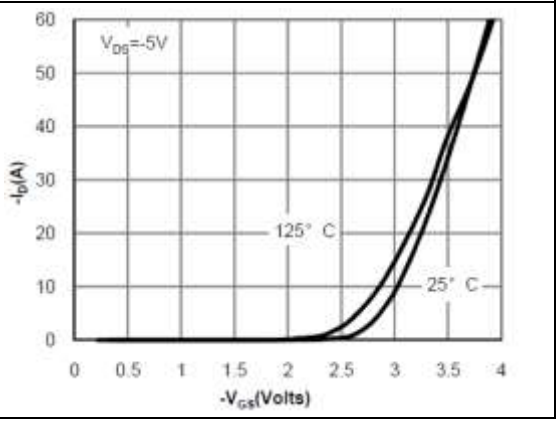


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

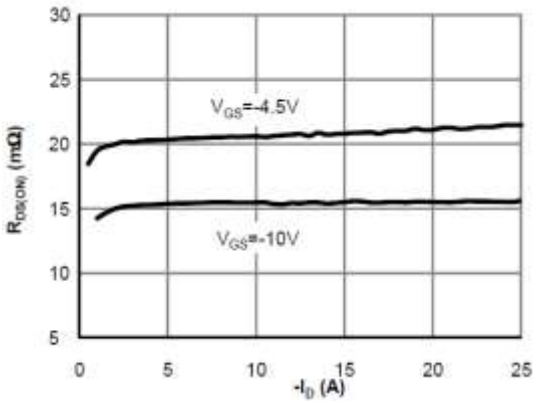


Figure 4. On-Resistance vs. Junction Temperature

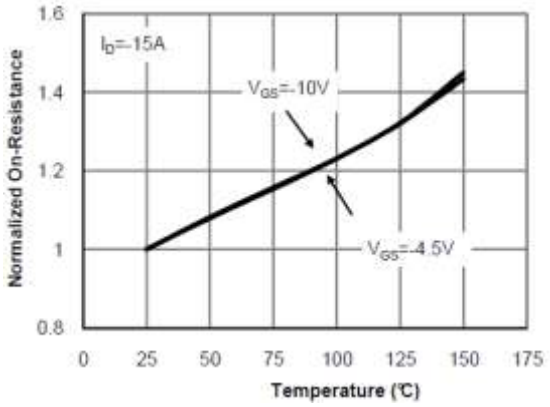


Figure 5. On-Resistance vs. Gate-Source Voltage

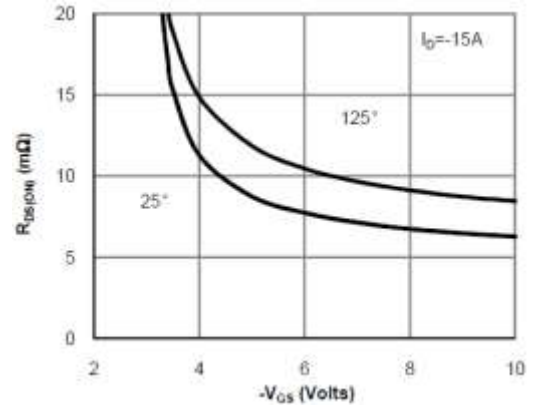


Figure 6. Body-Diode Characteristics

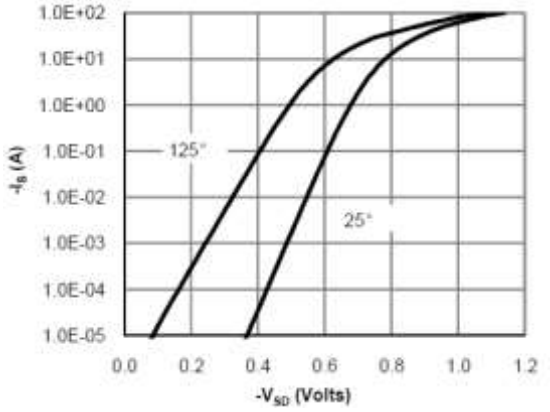


Figure 7. Gate-Charge Characteristics

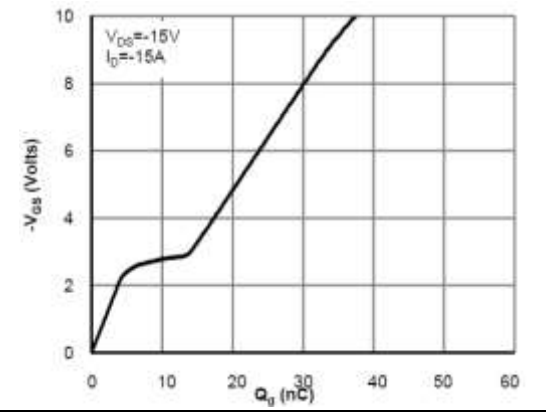


Figure 8. Capacitance Characteristics

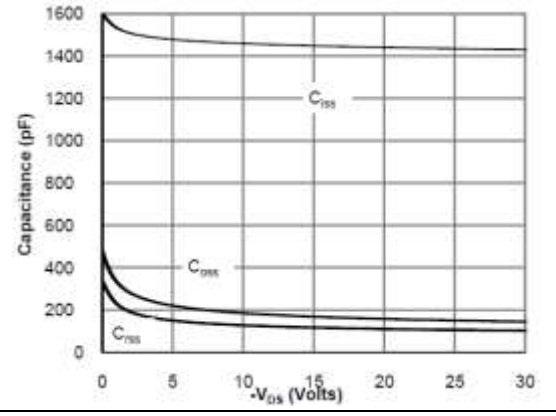


Figure 9. Maximum Forward Biased Safe Operating Area

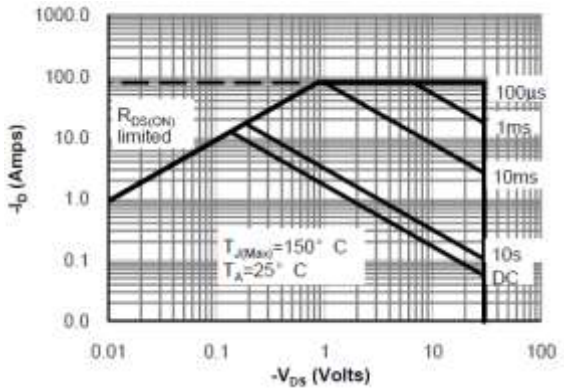


Figure 10. Single Pulse Power Rating Junction-to-Ambient

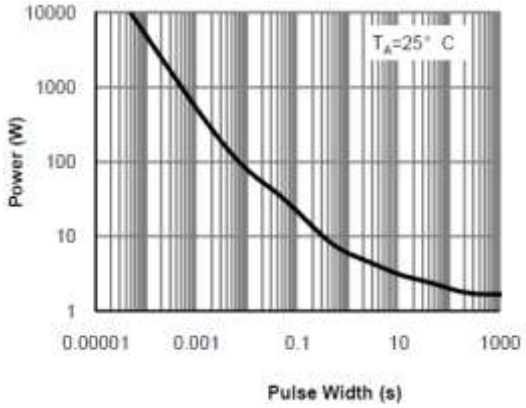
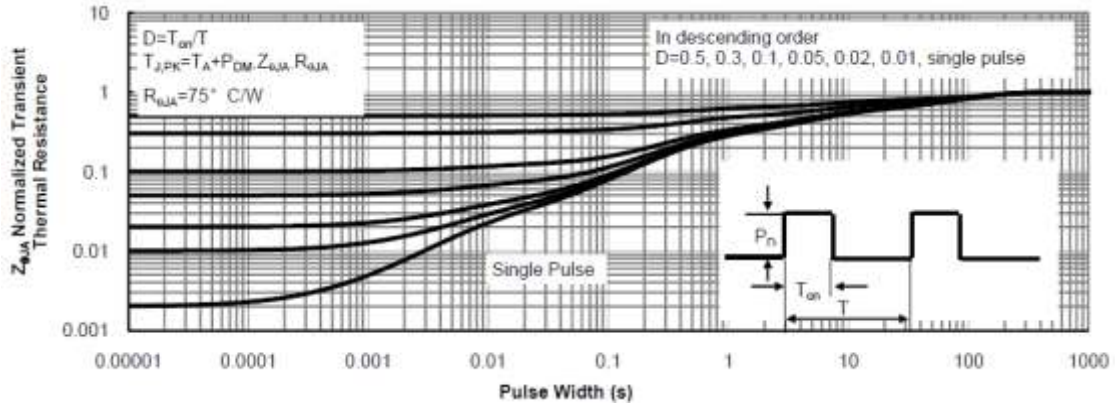
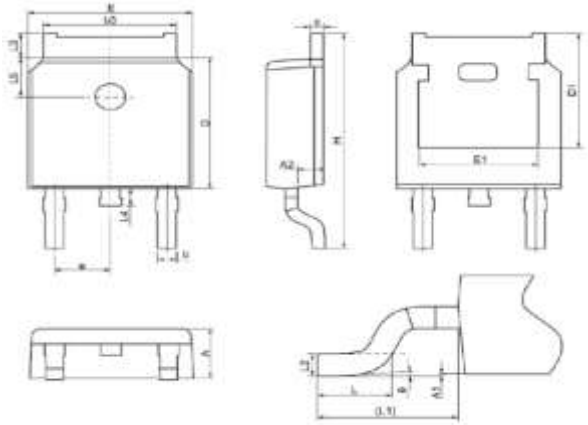


Figure 11. Normalized Maximum Transient Thermal Impedance



Physical Dimensions

TO-252



Symbol	Dimension (mm)			Symbol	Dimension (mm)		
	Min	Nom	Max		Min	Nom	Max
A	2.20	2.30	2.40	e	2.286(BSC)		
A1	0.00	-	0.20	H	9.40	10.10	10.50
A2	0.97	1.07	1.17	L	1.38	1.50	1.75
b	0.68	0.78	0.90	L1	2.90(REF)		
b3	5.20	5.33	5.50	L2	0.51(BSC)		
c	0.43	0.53	0.63	L3	0.88	-	1.28
D	5.98	6.10	6.22	L4	0.50	-	1.00
D1	5.30(REF)			L5	1.65	1.80	1.95
E	6.40	6.60	6.80	θ	0°	-	8°
E1	4.63	-	-	-	-	-	-